

# MV1830 TELETEXT DATA BUFFER

The MV1830 is a 64 x 9 sequential data buffer designed to be used with the MV1812 Teletext Data Acquisition Circuit. The MV1830 can be used singly, or can be cascaded so that the data from multiple VBI lines may be stored, allowing time for a slow system to read the data during the rest of the frame period.

#### **FEATURES**

- 10MHz Guaranteed Cascade Rate
- <150mW Power Dissipation at 10MHz</p>
- <55mW Standby</p>
- Single +5V Supply
- Tri-state Outputs

### **ASSOCIATED PRODUCTS**

MV1812 Teletext Data Acquisition circuit
SL9100 Teletext Data Slicer and Clock

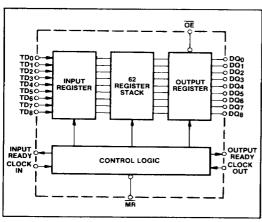


Fig.2 Block diagram

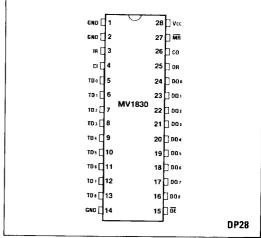


Fig.1 Pin connections - top view

#### **BUFFER OPERATION**

The MV1830 data buffer contains 64 nine-bit data registers. Data is initially loaded from the data inputs TD0-TD8 by applying a low to high transition on the Clock In (CI) input. Input Ready (IR) goes low indicating that data has been entered into the first register and the input is unable to accept more data. When CI goes low again, the fall through process begins (assuming that at least the second location is empty). The data in the first register is copied into the second and IR goes high indicating that the buffer is ready to accept new data.

Data falling through the registers stacks up at the output end. A high level on OR indicates that there is valid data waiting on DQ0-8. A Clock Out (CO) can then be used to shift data out of the buffer. The low to high transition on CO causes Output Ready (OR) to go low indicating that the data on the outputs may no longer be valid. When CO goes low, the data in the next to last register moves into the last register and OR goes high again.

The depth of the buffer can be extended by connecting the data outputs of one device to the inputs of the next, as shown in Fig.10. The Input Ready pin of the receiving device is connected to the Clock Out pin of the sending device. Similarly the Output Ready pin of the sending device is connected to the Clock In pin of the receiving device.

Master Reset (MR) is used to reset the control logic and remove the data from the outputs (i.e. resets to all zeros).

## **ELECTRICAL CHARACTERISTICS**

## Test conditions (unless otherwise stated):

 $T_{amb} = 0$ °C to +70°C, Vcc +4.5V to +5.5V

#### **DC Characteristics**

Characteristic	Symbol	Value		Unit	O - w diking a	
		Min.	Max.	Onit	Conditions	
Output high level	Vон	2.4		V	VIN = VIH OF VIL, IOH = -1mA	
Output low level	Vol		0.5	V	VIN = VIH OF VIL, TOL = 8mA	
Input high level	Vін	2		V		
Input low level	Vı		8.0	V		
Input leakage	lin	- 10	+10	μΑ	VIN = VIH OF VIL	
Output leakage GND ≤ Vouт ≤ Vcc	loz	- 50	+50	μΑ	Vcc = +5.5V	
Short circuit current	los		80	mA	Note 8	
Supply current	Icc		30	mA	Vcc = +5.5V	
• • •	1	1			T <sub>amb</sub> = 70°C	
		İ			ILOAD = 0mA	
Standby current			10	mA	Vcc = +5.5V	
		]			ILOAD = 0mA	
		l			All inputs at Vil	

## AC Characteristics - Using test circuit

Characteristic	Symbol	Value			
		Min.	Max.	Unit	Conditions
Maximum operating frequency	fo	10		MHz	Note 1
CI HIGH time	tehci"	30		ns	
CI LOW time	<b>t</b> PLCI	40		ns	
Data setup to CI	tsci	0		ns	Note 2
Data hold from CI	tHCI (a)	50		ns	Note 2 and 3
	tHCI (b)	tPHCI - 5		ns	1
Delay, CI HIGH to IR LOW	tolir		30	ns	1
Delay, CI LOW to IR HIGH	tohir		40	ns	
CO HIGH time	tenco	30		ns	
CO LOW time	tplco	40		ns	
Delay, CO HIGH to OR LOW	tolor		30	ns	
Delay, CO LOW to OR HIGH	tonor		40	ns	İ
Data setup to OR HIGH	tson	-20		ns	
Data hold from CO LOW	thco	10		ns	
IR pulse HIGH	t PIR	9		ns	
OR pulse HIGH	t POR	10		ns	
Data setup to IR	tsir	0		ns	Note 5
Data hold from IR	tein	50		ns	Note 5
Bubble through time	tвт	1	2400	ns	
MR pulse width	t <sub>PMR</sub>	60		ns	Note 6
MR HIGH to CI HIGH	toci	60		ns	
MR LOW to OR LOW	toon		60	ns	
MR LOW to IR HIGH	toia		60	ns	
MR LOW to output LOW	t LZMR		60	ns	Note 4
Output valid from OE LOW	tooe	Į.	60	ns	
Output HIGH-Z from OE HIGH	t HZOE		60	ns	

NOTES 1. 1/fo > tehci + tohin, 1/fo > tehco + tohon.

2. tsc and thic apply when memory is not full.
3. Hold time is the lesser of the two parameters (a) and (b).

All data outputs will be at LOW level after reset goes high until data is entered into the buffer
 These times apply when the device is full and Cl is held high.
 For cascade applications, them must be double that specified above.

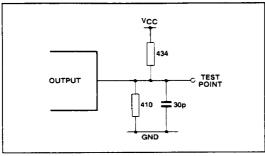


Fig.3 Test circuit

## **ABSOLUTE MAXIMUM RATINGS (Note 7)**

Supply voltage Vcc -0.5V to 7.0V Input voltage Vin (see Note 9) -0.9V to Vcc +0.9V DC voltage applied to output when high impedance -0.5V to 7.0V Clamp diode current per pin (see Note 8) +18mA Storage temperature Ts -65 °C to +150 °C

#### NOTES

 Exceeding these ratings may cause permanent damage. Functional operation under these conditions is not implied.
 Maximum dissipation or 1 second should not be exceeded, only one output to be tested at any one time.

9. Input voltages more negative than —0.9V cause clamp diode current to flow. The maximum negative voltage depends on the source impedance.

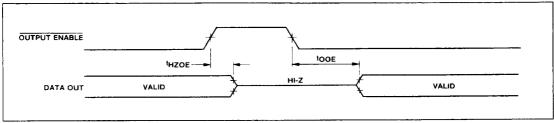


Fig.4 Output enable timing

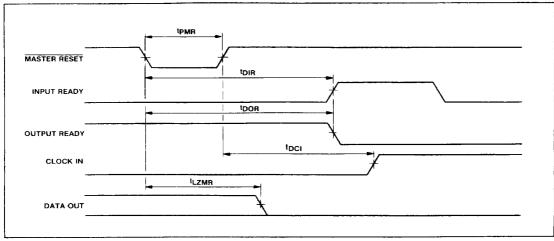


Fig.5 Master reset timing

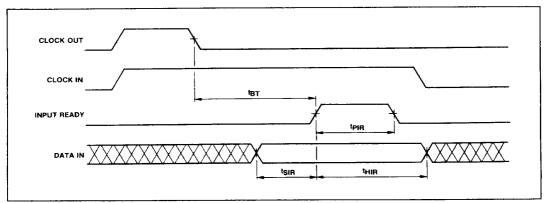


Fig.6 Data Out to Data In bubble through time

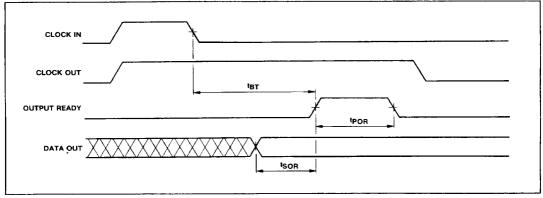


Fig.7 Data In to Data Out bubble through time

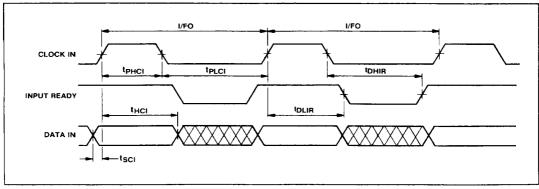


Fig.8 Switching waveforms - Data In timing

1000

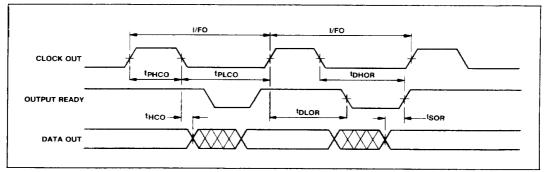


Fig.9 Switching waveforms - Data Out timing

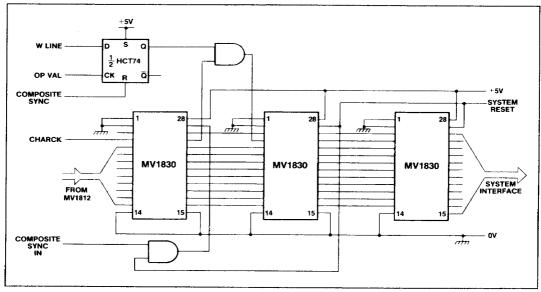


Fig.10 Interface to MV1812

#### **USER NOTES**

- When the buffer is empty the last word read will remain on the outputs until the master reset is strobed or a new data word falls through to the output. However, OR will remain LOW, indicating data at the output is not valid.
- When the output changes as a result of a pulse on CO, the OR signal always goes LOW before there is any change in output data.
- 3. If CO is held HIGH while the memory is empty and a word is written into the input, that word will ripple through the buffer to the output. OR will go HIGH for one internal cycle (tpon) and then go back LOW again. The stored word

will remain on the outputs. If more words are written into the buffer, they will line up behind the first word and will not appear on the outputs until CO has been brought LOW.

4. When the master reset is brought LOW, the outputs are cleared to LOW, IR goes HIGH and OR goes LOW. If Cl is HIGH when the master reset goes HIGH then the data on the inputs will be written into the buffer and IR will return to the LOW state until Cl is brought LOW. If Cl is LOW when the master reset is ended, the IR will go HIGH, but the data on the inputs will not enter the buffer until Cl goes HIGH.